



Material Content Data Sheet



Sales Product Name	IPP023N04N G			Issued		29. August 2013		
MA#	MA000787446							
Package	PG-TO220-3-123			Weight*		2026.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	0.22	0.22	2183	2183
leadframe	non noble metal	iron	7439-89-6	1.407	0.07		694	
	inorganic material	phosphorus	7723-14-0	0.422	0.02		208	
	non noble metal	copper	7440-50-8	1404.801	69.30	69.39	693110	694012
wire	non noble metal	aluminium	7429-90-5	6.397	0.32	0.32	3156	3156
encapsulation	organic material	carbon black	1333-86-4	2.335	0.12		1152	
	plastics	epoxy resin	-	67.711	3.34		33408	
	inorganic material	silicondioxide	60676-86-0	513.671	25.34	28.80	253438	287998
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10589	10589
plating	non noble metal	nickel	7440-02-0	1.764	0.09	0.09	870	870
solder	non noble metal	antimony	7440-36-0	0.242	0.01		119	
	noble metal	silver	7440-22-4	0.604	0.03		298	
	non noble metal	tin	7440-31-5	1.571	0.08	0.12	775	1192
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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